



S O S G R O U P

**BESI Datacon 2200 evo
Multi-chip die bonder
SN 950 2218 2199
Vintage 2010**

BESI Datacon 2200 evo
Multi-chip die bonder
SN 950 2218 2199
Vintage 2010
located Nijmegen the Netherlands

The Datacon 2200 evo high-accuracy multi-chip die bonder provides the ultimate flexibility for die attach as well as for flip chip applications. Equipped with integrated dispenser, 12" wafer handling, automatic tool changer, and application specific tooling, the Datacon 2200 evo is prepared for present and future processes and products.

Key Features

High Performance at High Accuracy

Highest accuracy $\pm 10 \mu\text{m}$ @ 3 Sigma (7 μm on request)

High productivity, low cost-of-ownership

Up to 4 working heads in one machine

Multi-Chip Capability

Single pass production for complex products

Die attach, flip chip, multi-chip in one machine

Epoxy writing & stamping, flux dipping

Unbeaten Flexibility

Die pick from wafer, waffle pack, gel pack, feeder

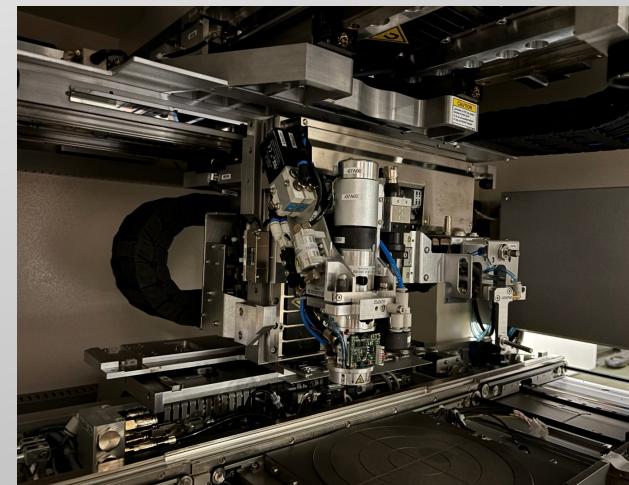
Die place to carrier, boat, substrate, PCB, lead frame, wafer

Hot and cold processes supported: epoxy, soldering, thermo-compression

MCM, SiP, Hybrids



BESI Datacon 2200 evo
Multi-chip die bonder
SN 950 2218 2199
Vintage 2010
located Nijmegen the Netherlands



Solutions on Silicon BV

Your service partner for LAM Research Equipment

- **Equipment Support**

PM, CM, Trouble shooting, Upgrading, Training and Onsite Service Contracts

- **Process Support**

Process design, Improvement, Fab-to-Fab Transfer and Integration

- **Refurbishment**

From custom to complete refurbishment

- **Relocation**

Auditing, Fingerprinting, Decommissioning, Installation, Acceptance

- **Materials**

Supplier of first class second source materials

